



# **MDD1501**

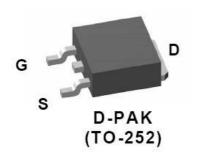
# Single N-channel Trench MOSFET 30V, 67.4A, 5.6mΩ

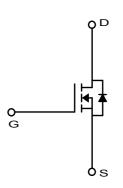
#### **General Description**

The MDD1501 uses advanced MagnaChip's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance and excellent quality. MDD1501 is suitable device for DC to DC converter and general purpose applications.

#### **Features**

- V<sub>DS</sub> = 30V
- $I_D = 67.4A @V_{GS} = 10V$
- $^{\square}$  R<sub>DS(ON) (MAX)</sub> < 5.6mΩ @V<sub>GS</sub> = 10V < 8.6mΩ @V<sub>GS</sub> = 4.5V
- 100% UIL Tested
- 100% Rg Tested





#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	30	V		
Gate-Source Voltage		$V_{GSS}$	±20	V	
	T <sub>C</sub> =25°C		67.4		
Continuous Drain Current (1)	T <sub>C</sub> =70°C	Ī.	53.9	A	
	T <sub>A</sub> =25°C	− I <sub>D</sub>	25.1 <sup>(3)</sup>		
	T <sub>A</sub> =70°C	7	20.2 <sup>(3)</sup>		
Pulsed Drain Current		I <sub>DM</sub>	100	Α	
	T <sub>C</sub> =25°C		44.6		
Power Dissipation	T <sub>C</sub> =70°C		28.5	W	
	T <sub>A</sub> =25°C	P <sub>D</sub>	6.2 <sup>(3)</sup>		
	T <sub>A</sub> =70°C	7	4.0 <sup>(3)</sup>		
Single Pulse Avalanche Energy (2)		E <sub>AS</sub>	94	mJ	
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Rating	Unit	
Thermal Resistance, Junction-to-Ambient (1)	$R_{\theta JA}$	20.0	°C/W	
Thermal Resistance, Junction-to-Case	R <sub>BJC</sub> 2.8			

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# **Ordering Information**

Part Number	Temp. Range	Package	Packing	Quantity	Rohs Status
MDD1501RH	-55~150°C	D-PAK	Tape & Reel	3000 units	Halogen Free

# Electrical Characteristics (T<sub>J</sub> =25°C)

Characteristics	Symbol	Test Condition		Min	Тур	Max	Unit
Static Characteristics	•	•					•
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$I_D = 250 \mu A, V_{GS} = 0V$ $V_{DS} = V_{GS}, I_D = 250 \mu A$		30	-	-	- v
Gate Threshold Voltage	$V_{GS(th)}$			1.55	1.95	2.7	
D : 0.10%0		V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V		-	-	1	
Drain Cut-Off Current I <sub>DSS</sub> T <sub>J</sub> =55°C		T <sub>J</sub> =55°C	-	-	5	μA	
Gate Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±0.1	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A		-	4.9	5.6	mΩ
Drain-Source ON Resistance	R <sub>DS(ON)</sub>		T <sub>J</sub> =125°C	-	7.1	8.1	
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 16A	1	-	7.2	8.6	
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A		-	35	-	S
Dynamic Characteristics							•
Total Gate Charge	Q <sub>g(10V)</sub>	V <sub>DS</sub> = 15.0V, I <sub>D</sub> = 20A, V <sub>GS</sub> = 10V		15.5	20.7	25.9	
Total Gate Charge	Q <sub>g(4.5V)</sub>			7.6	10.1	12.6	nC
Gate-Source Charge	$Q_{gs}$			-	3.7	-	
Gate-Drain Charge	$Q_{gd}$			-	2.9	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15.0V, V <sub>GS</sub> = 0V, f = 1.0MHz		1013	1350	1688	
Reverse Transfer Capacitance	C <sub>rss</sub>			99	132	165	pF
Output Capacitance	C <sub>oss</sub>			195	261	326	
Turn-On Delay Time	t <sub>d(on)</sub>			-	8.8	-	
Rise Time	t <sub>r</sub>	$V_{GS} = 10V, V_{DS} = 15.0V$		-	12.2	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = 20A$ , $R_G = 3.0\Omega$		-	29.5	-	ns
Fall Time	t <sub>f</sub>			-	8.6	-	
Gate Resistance	Rg	f=1 MHz		-	1.5	2.5	Ω
Drain-Source Body Diode Characteristics	L	•					
Source-Drain Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> = 20A, V <sub>GS</sub> = 0V		-	8.0	1.1	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			-	22.4	33.6	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 20A, dl/dt = 100A/μs		-	14.0	21.0	nC

#### Note:

<sup>1.</sup> Surface mounted FR-4 board by JEDEC (jesd51-7) 2. E<sub>AS</sub> is tested at starting Tj =  $25\,^{\circ}$ C, L = 0.1mH, I<sub>AS</sub> = 24.0A, V<sub>DD</sub> = 27V, V<sub>GS</sub> = 10V. 3. T < 10sec.

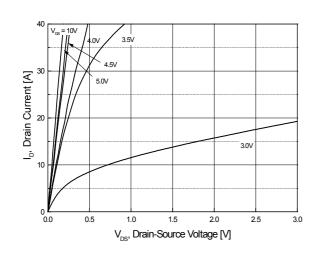


Fig.1 On-Region Characteristics

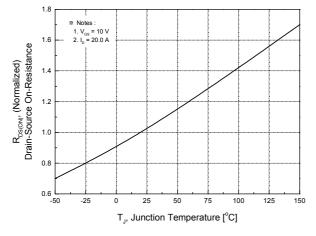


Fig.3 On-Resistance Variation with Temperature

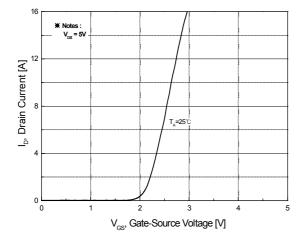


Fig.5 Transfer Characteristics

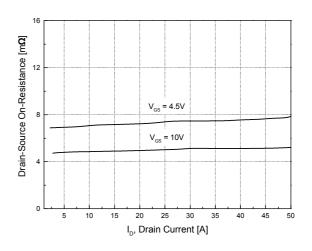


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

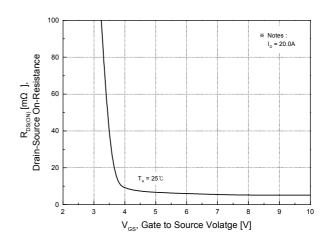


Fig.4 On-Resistance Variation with Gate to Source Voltage

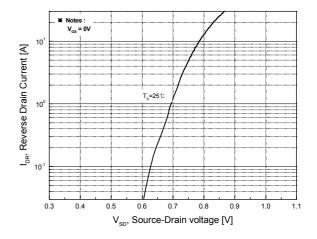


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature

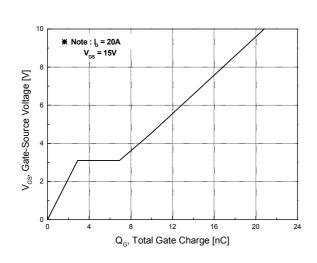


Fig.7 Gate Charge Characteristics

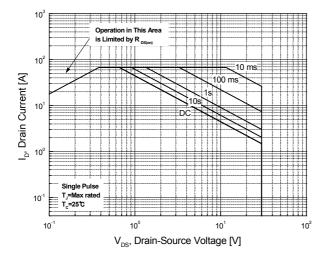


Fig.9 Maximum Safe Operating Area

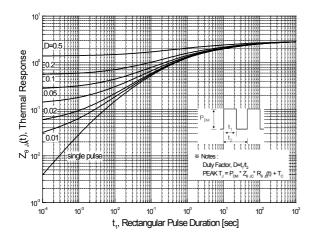


Fig.11 Transient Thermal Response Curve

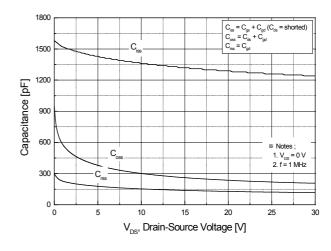


Fig.8 Capacitance Characteristics

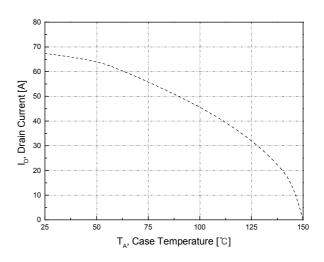
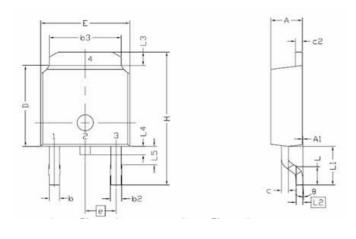


Fig.10 Maximum Drain Current vs. Case Temperature

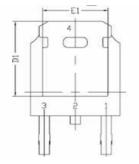
# **Package Dimension**

# **D-PAK (TO-252)**

### Dimensions are in millimeters, unless otherwise specified



Symbol	Min.	Nom.	Max.				
Е	6,35	-	6,73				
L	1,40	1,52	1,78				
L1	2,74 REF						
L2		0,508 BCS					
L2 L3	0,89	-	1,27				
L4	_	_	1,02				
L5	1,14	-	1,52				
D	5,97	6,10	6,22				
Н	9,40	-	10,41				
b	0,64	-	0,89				
b2	0,76	-	1,14				
b3	4,95	-	5,46				
е	2,286 BSC						
Α	2,18	-	2,39				
A1	-	-	0,13				
С	0,46	-	0,61				
c2	0,46	-	0,89				
D1	5,21	-	_				
E1	4,32	-	_				
Θ	0,00	-	10,00				



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